

L Number	Hits	Search Text	DB	Time stamp
1	134	(low near resistance)and (interconnect near line)and (cooper or Cu) and (Aluminum or Al)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 17:26
7	252	(low near resistance)and (interconnect near line)and (copper or Cu) and (Aluminum or Al)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 17:27
13	230	(low near resistance)and (interconnect near line)and (Aluminum or Al)and over and (copper or Cu)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 17:34
19	88	(low near resistance)and (interconnect near line)and (Aluminum or Al)same over same (copper or Cu)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:03
25	2	(low near resistance)and (interconnect near line)and (Aluminum or Al)near over near (copper or Cu)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 17:40
31	117	"5262354"	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 17:50
37	0	(low near resistance)and (interconnect near line)and (Aluminum or Al)adj over adj (copper or Cu)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:06
43	593	(low near resistance)and (interconnect near line)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:06
55	0	((low near resistance)and (interconnect near line)) and ((Aluminum or Al)adj over adj (copper or Cu))	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:06
49	15	(Aluminum or Al)adj over adj (copper or Cu)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:35
61	14123	(Aluminum or Al)with(over or above) with (copper or Cu)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:37
67	14747	43and ((Aluminum or Al)with(over or above) with (copper or Cu))	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:37
73	4519	(Aluminum or Al)with(over) with (copper or Cu)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:38
79	41	((low near resistance)and (interconnect near line)) and ((Aluminum or Al)with(over) with (copper or Cu))	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:46
85	21755	Semiconductor and via and (copper or Cu) and (aluminum or Al)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:49
91	19755	Semiconductor and via and(aluminum or Al) and (above) and (copper or Cu)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:50
97	2278	Semiconductor and via and(aluminum or Al) and (above) and (copper or Cu) and (low near resistance)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:56

103	7184	interconnect near line	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:52
109	149	(Semiconductor and via and(aluminum or Al) and (above) and (copper or Cu) and (low near resistance)) and (interconnect near line)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:54
115	21	Semiconductor and via and(aluminum or Al) adj (above) and (copper or Cu) and (low near resistance)	USPAT; EPO; JPO; DERWENT; USOCR	2002/08/22 18:58